

1.Features

- $V_{DS(V)}=60V$
- $I_D=38A$
- $R_{DS(ON)}<21m\Omega(V_{GS}=10V)$
- $R_{DS(ON)}<25m\Omega(V_{GS}=6V)$
- Low gate charge (33nC typical).
- Fast switching speed.
- High performance trench technology for extremely low $R_{DS(ON)}$.

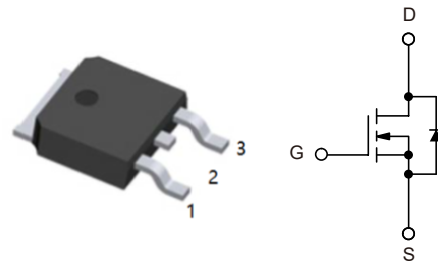
3.Application

- DC/DC converter
- Motor drives

4.Pinning information

Pin	Symbol	Description
1	G	GATE
2	D	DRAIN
3	S	SOURCE

TO-252(DPAK)
top view



5.Absolute Maximum Ratings $T_A=25^{\circ}C$

Parameter	Symbol	Rating	Units
Drain - Source Voltage	V_{DSS}	60	V
Gate - Source Voltage	V_{GSS}	± 20	
Maximun Drain Current - Continuous (Note 1)	I_D	38	A
(Note 1a)		8.5	
Maximum Drain Current - Pulsed		100	
Maximum Power Dissipation	P_D	60	W
		2.8	
		1.3	W
Operating and Storage Junction Temperature Range	T_J, T_{STG}	-55 to 150	$^{\circ}C$



6.Thermal Characteristics

Parameter		Symbol	Rating	Units
Thermal Resistance, Junction to Case	(Note 1)	$R_{\theta JC}$	2.1	°C/W
Thermal Resistance, Junction to Ambient	(Note 1b)	$R_{\theta JA}$	96	°C/W



7. Electrical Characteristic ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

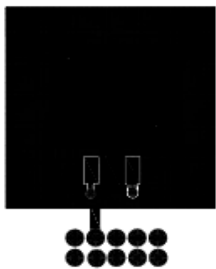
Parameter	Symbol	Conditions	Min	Typ	Max	Units
Off Characteristics						
Single Pulse Drain-Source Avalanche Energy	W_{DSS}	$V_{DD}=30\text{V}$, $I_D=38\text{A}$			140	mJ
Maximum Drain-Source Avalanche Current	I_{AR}				38	A
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	60			V
Breakdown Voltage Temperature Coefficient	$\frac{\Delta BV_{DSS}}{\Delta T_J}$	$I_D=250\mu\text{A}$ Referenced to 25°C		60		mV/ $^{\circ}\text{C}$
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=48\text{V}$, $V_{GS}=0\text{V}$			1	μA
Gate-Body Leakage Current Forward	I_{GSSF}	$V_{GS}=20\text{V}$, $V_{DS}=0\text{V}$			100	nA
Gate-Body Leakage Current Reverse	I_{GSSR}	$V_{GS}=-20\text{V}$, $V_{DS}=0\text{V}$			-100	nA
On Characteristics (Note 2)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	1		2.2	V
Gate Threshold Voltage Temperature Coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	$I_D=250\mu\text{A}$ Referenced to 25°C		-6.4		mV/ $^{\circ}\text{C}$
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10\text{V}$, $I_D=8.5\text{A}$ $V_{GS}=6\text{V}$, $I_D=7.5\text{A}$		17 19	21 25	m Ω m Ω
On-State Drain Current	$I_{D(on)}$	$V_{GS}=10\text{V}$, $V_{DS}=5\text{V}$	50			A
Forward Transconductance	g_{FS}	$V_{DS}=5\text{V}$, $I_D=8.5\text{A}$		30		S
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=30\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$		1835		pF
Output Capacitance	C_{oss}			210		pF
Reverse Transfer Capacitance	C_{rss}			90		pF



Switching Characteristics (Note 2)						
Turn-On Delay Time	t _{D(on)}	V _{DD} =30V, I _D =1A V _{GS} =10V, R _{GEN} =6Ω		15	27	ns
Turn-On Rise Time	t _r			9	18	ns
Turn-Off Delay Time	t _{D(off)}			35	56	ns
Turn-Off Fall Time	t _f			16	26	ns
Total Gate Charge	Q _g	V _{DS} =30V, I _D =8.5A, V _{GS} =10V		33	46	nC
Gate-Source Charge	Q _{gs}			6.5		nC
Gate-Drain Charge	Q _{gd}			7.5		nC
Drain–Source Diode Characteristics and Maximum Ratings						
Maximum Continuous Drain–Source Diode Forward Current	I _s				2.3	A
Drain–Source Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _s =2.3A (Note 2)		0.75	1.2	V

Notes:

1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient resistance where the case thermal reference is defined as the drain tab.
- $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design.



a) $R_{\theta JA}=45^{\circ}C/W$ when mounted on a 1 in² pad of 2oz copper.



b) $R_{\theta JA}= 96^{\circ}C/W$ when mounted on a 0.076 in² pad of 2oz copper.

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width $\leq 300\ \mu s$, Duty Cycle $\leq 2.0\%$.



8.1 Typical characteristic

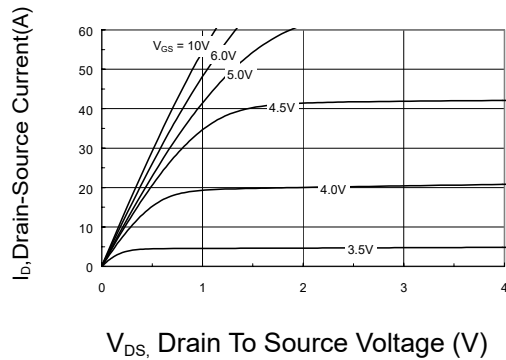


Figure 1: On-Region Characteristics

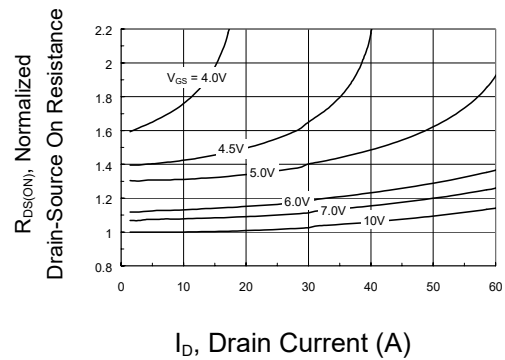


Figure 2: On-Resistance Variation with Drain Current and Gate Voltage

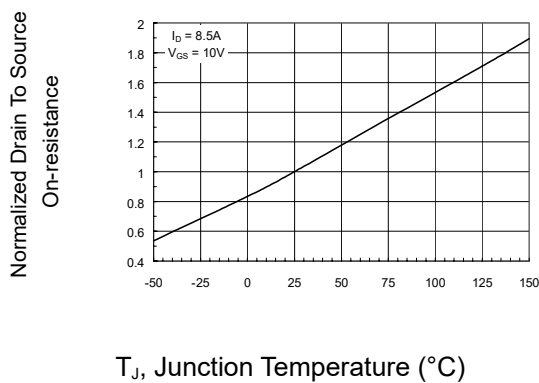


Figure 3: On-Resistance Variation with Temperature

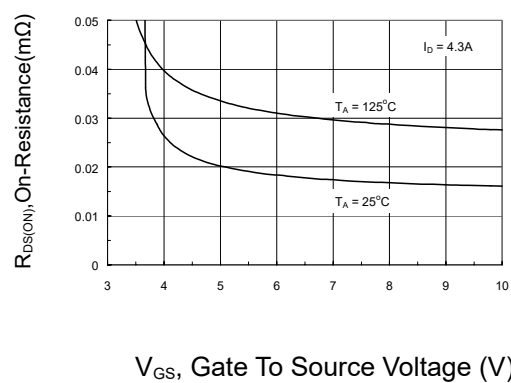


Figure 4: On-Resistance Variation with Gate-to-Source Voltage

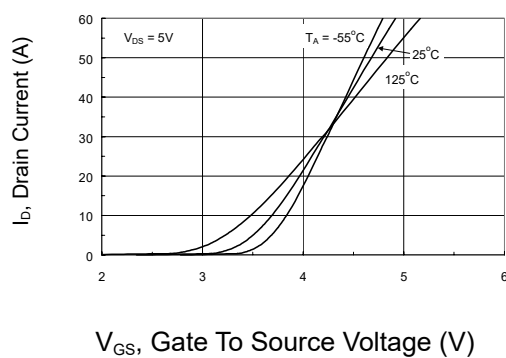


Figure 5: Transfer Characteristics

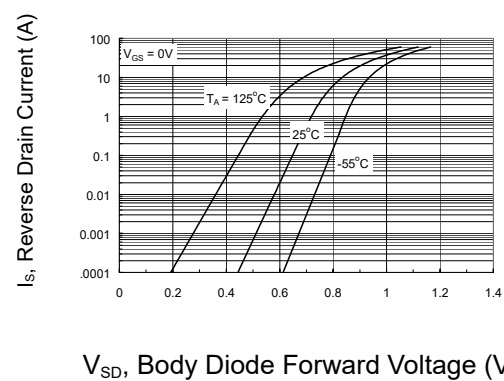


Figure 6: Body Diode Forward Voltage Variation with Source Current and Temperature



8.2 Typical characteristic

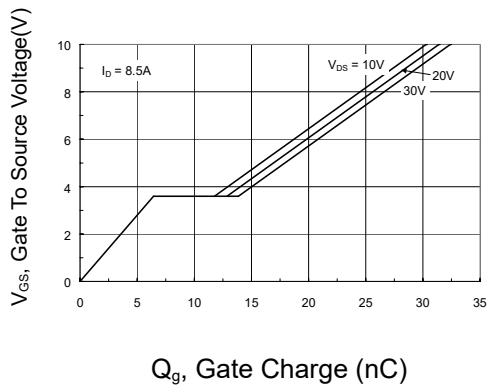


Figure 7: Gate Charge Characteristics

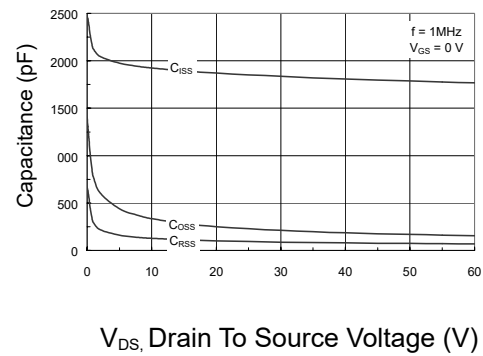


Figure 8: Capacitance Characteristics

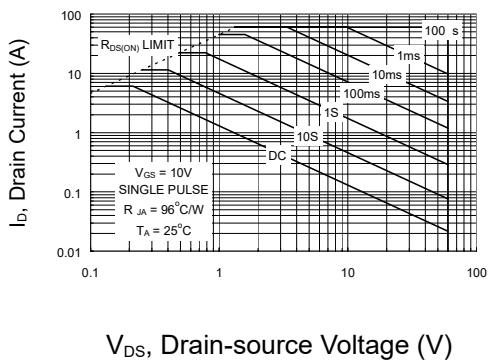


Figure 9: Maximum Safe Operating Area

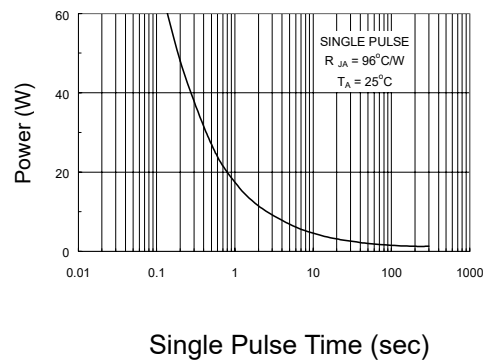


Figure 10: Single Pulse Maximum Power Dissipation

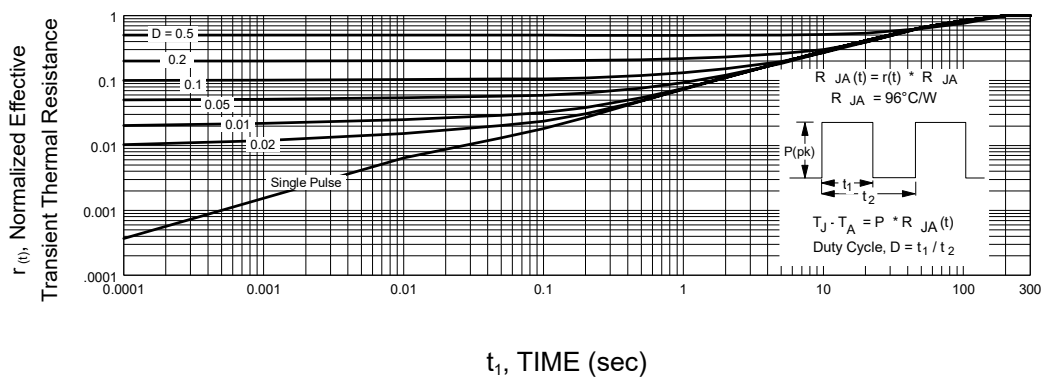
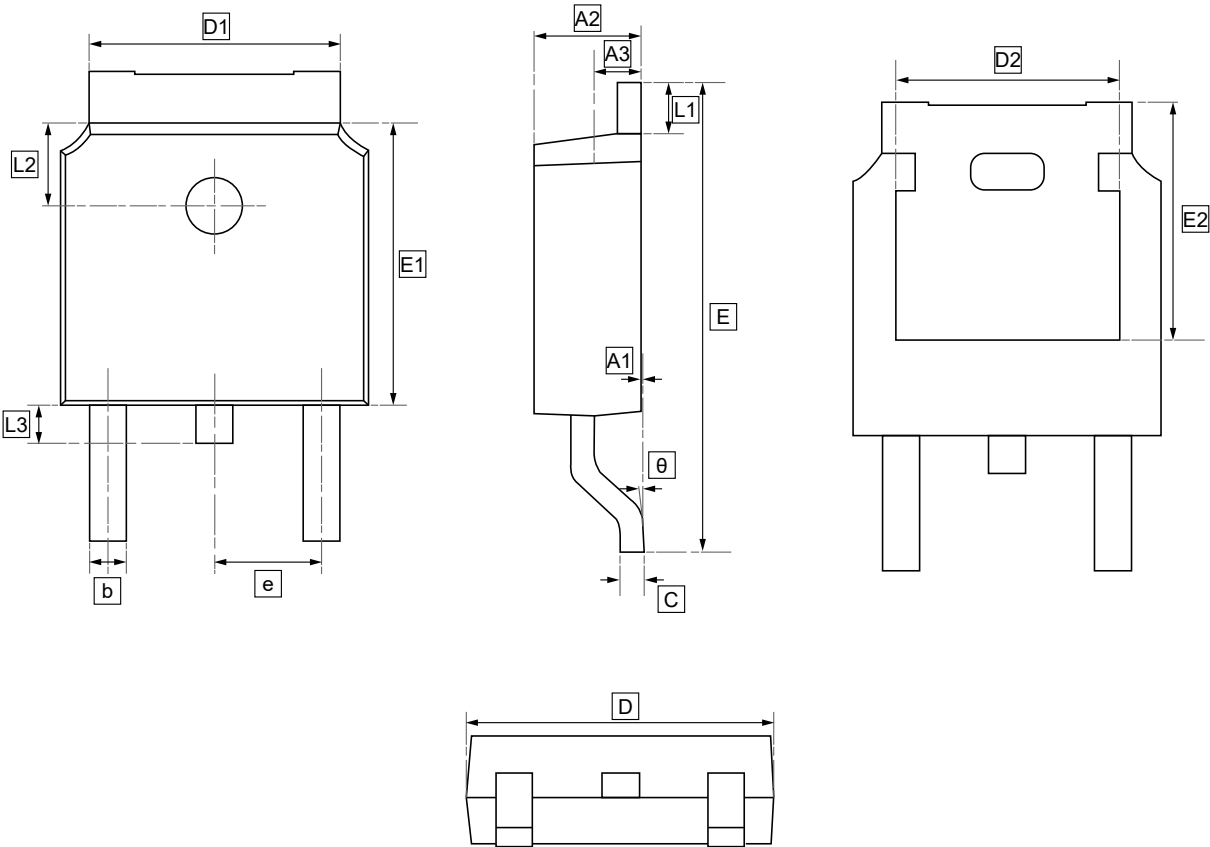


Figure 11: Transient Thermal Response Curve



9.TO-252 Package Outline Dimensions

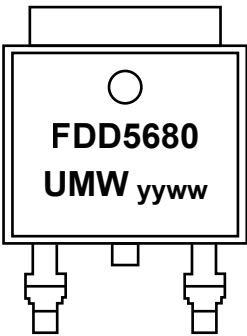


DIMENSIONS (mm are the original dimensions)

Symbol	A1	A2	A3	b	c	D	D1	D2	E	E1	E2	e	L1	L2	L3	θ
Min	0.00	2.18	0.90	0.65	0.46	6.35	4.95	4.32	9.40	5.97	5.21	2.286	0.89	1.70	0.60	0.00
Max	0.13	2.39	1.10	0.85	0.61	6.73	5.46	4.90	10.41	6.22	5.38		BSC	1.27	1.90	1.00



10.Ordering information



yy: Year Code
ww: Week Code

Order Code	Package	Base QTY	Delivery Mode
UMW FDD5680	TO-252	2500	Tape and reel



11.Disclaimer

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